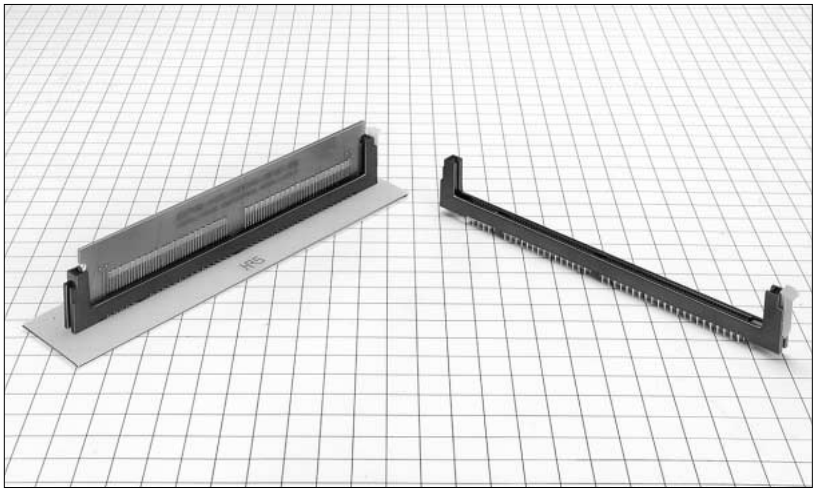
查询SX4AB-168S-1.27DSA供应商

1.27mm Pitch 8Byte DIMM Socket

SX4 Series



■Features

1. 8Byte DIMM Compliant Socket

The SX4 series are a socket compliant to "8Byte DIMM" standardized at JEDEC.

2. JEDEC Standard MO-161

The applicable module board 1.27mm pitch 168 pos. for double-sided connection.

3. Easy PC Board Pattern Design

The lead length for soldering dip connection on the board is 1.27mm, row-row 1.27mm, 1.6mm, 1.905mm, and staggered alignment in 4 rows.

4. Compatible with 5V and 3.3V Operating Voltage Module Board

5. Prevents Mis-insertion in Module Board

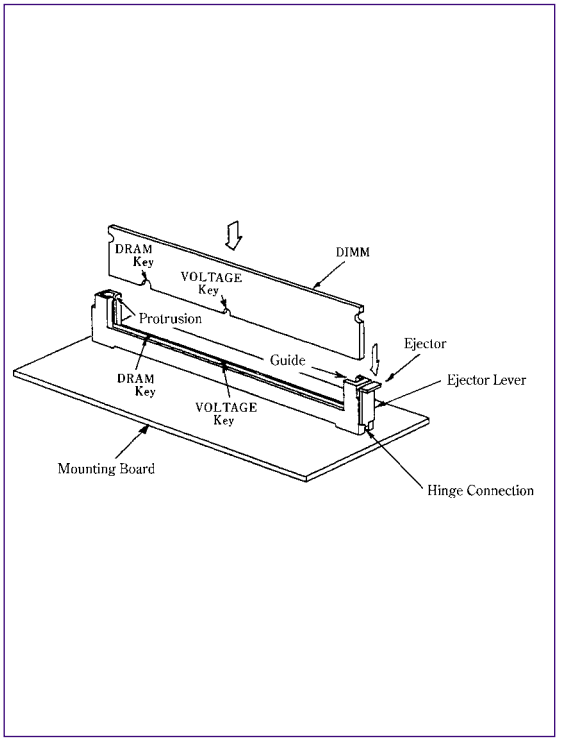
The key mechanism prevents mis-insertion in the module board.

6. Prevents Displacement of Module Board

The structure to sustain the module board on both sides prevents displacement of the module board.

7. Easy Insertion and Extraction of Module Board

The unique ejector mechanism facilitates to remove the module board. with pushing the injector.
In addition, marginal space is not needed for insertion and extraction actions.



■Applications

Workstations, computers, personal computers, PPC, business machines, measuring instruments, etc.

■Product Specifications

Rating	Operating Temperature Range	-55℃ to +85℃	Storage Temperature Range -55℃ to +85℃
	Voltage rating	100V AC	
	Current rating	0.5A	

Item	Specification	Condition
1. Contact Resistance	30m ohms min.	100mA DC
2. Insulation Resistance	1000M ohms min.	250V DC
3. Withstanding voltage	No flashover or insulation breakdown.	250V AC / 1 minute
4. Insulator/Extraction Force	196N max.	Measured with the 1.37±0.002mm gauge
5. Vibration	No electrical discontinuity of 1μs or more	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 50 minutes in each of the 3 directions.
6. Moisture Resistance	Contact resistance: 50m ohms max. Insulation Resistance: 1000M ohms min.	96 hours at temperature of 40℃ and humidity of 90% to 95%
7. Temperature Cycle	Contact resistance: 50m ohms max. Insulation Resistance: 1000M ohms min.	Tested for 5 cycles under following condition Temperature : -55→ +5 to 35→ +85→ +5 to 35℃ Time : 30→ 10 to 15→ 30→ 10 to 15 minutes
8. Operating Life	Contact resistance: 50m ohms max.	30 cycles
9. Salt spray	Contact resistance: 50m ohms max.	Exposed to density 5% salt water for 48 hours

■Material

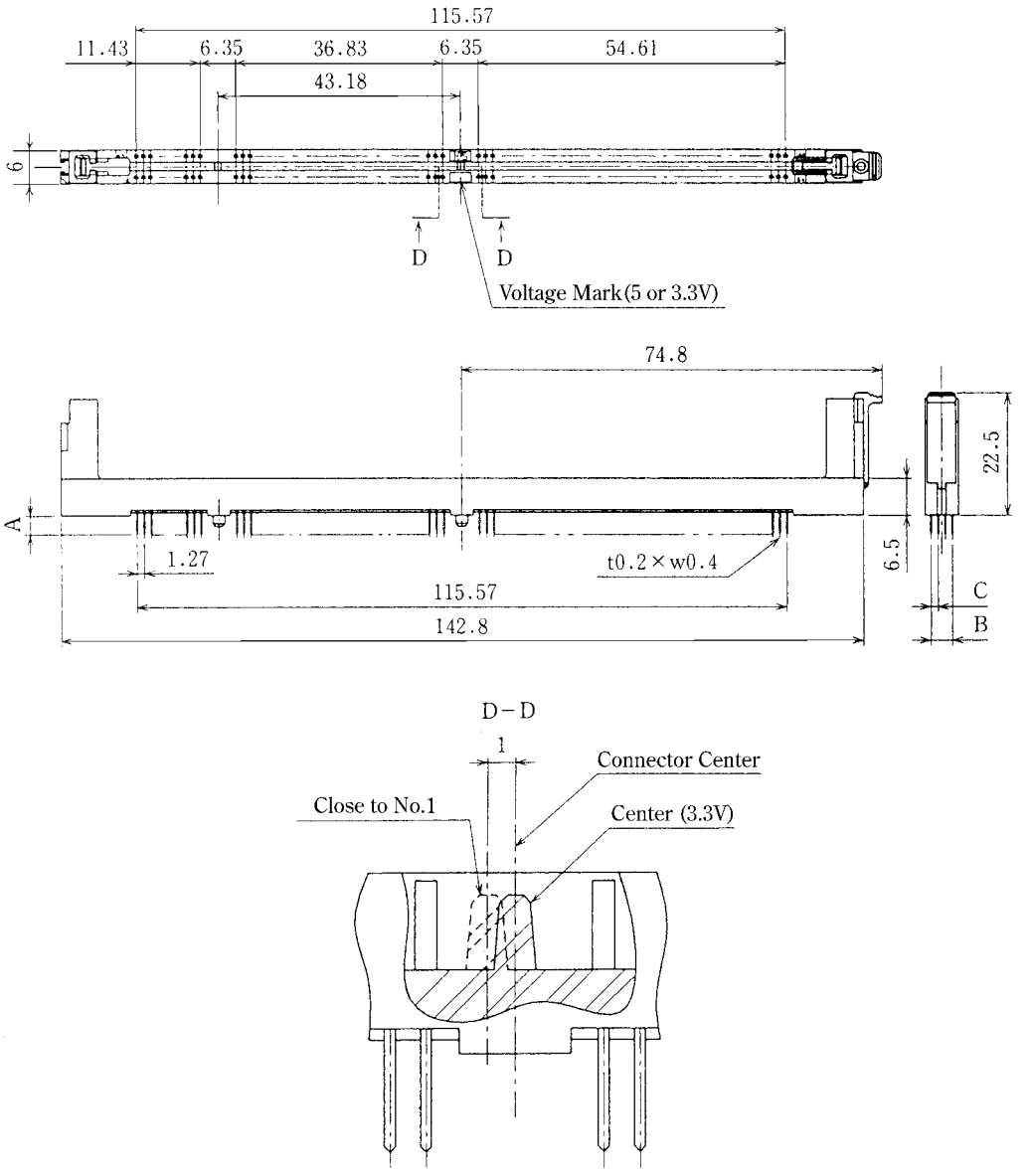
Part	Material	Finish
Contact	Phosphor copper	Selective gold plating
Insulator	PPS(UL94V-0)	———
Ejector	Polyamid	———

■Ordering Information

SX4 A B - 168 S - 1.27 DSA
❶ ❷ ❸ ❹ ❺ ❻ ❼

❶Series Name: SX4	❹Number of Contacts: 168
❷DIMM Key: A: 5V type B: 3.3V type	❺Contact Type: Female
	❻Contact Pitch: 1.27mm
❸Positioning boss A: Without boss B: With boss	❼Contact type (row interval x lead length) DSA: 1.6mm x 3.5mm DSD: 1.27mm x 3.5mm DSH: 1.905mm x 3.5mm

■168 Contacts



Unit: mm

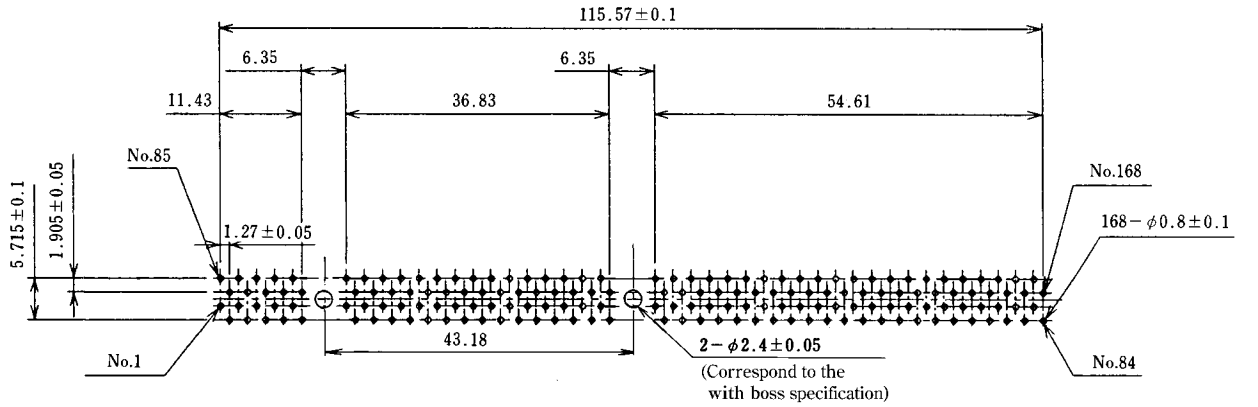
Part Number	CL No.	Number of Contacts	A	B	C	Boss	Voltage Key (Note)
SX4AB-168S-1.27DSA	530-0100-8	168	3.5	4.8	1.6	With boss	5.0V
SX4BA-168S-1.27DSA	530-0103-6		3.5	4.8	1.6	Without boss	3.3V
SX4BA-168S-1.27DSD	530-0112-7		3.5	3.81	1.27	Without boss	3.3V
SX4AB-168S-1.27DSH	530-0115-5		3.5	5.72	1.905	With boss	5.0V

Note : 3.3V and 5.0V correspond to the 8Byte DIMM voltage key.

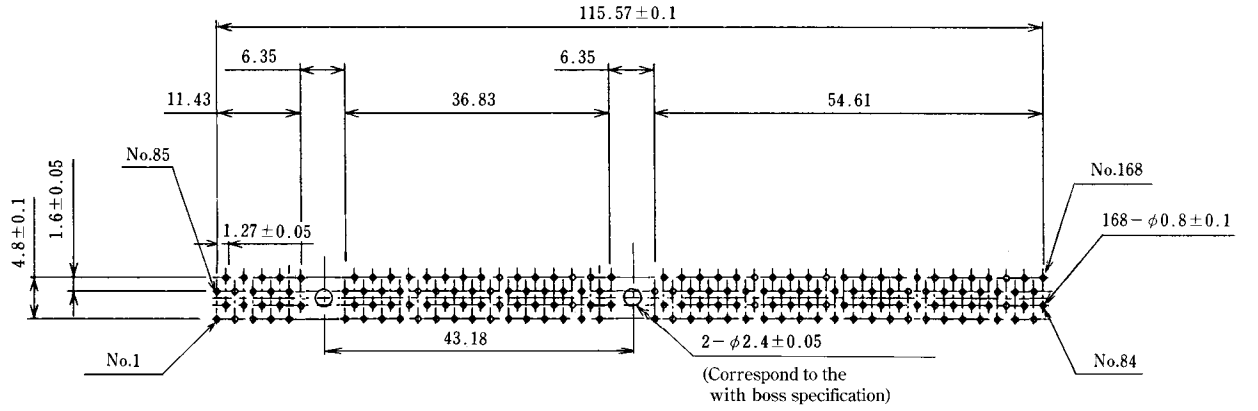
◆PCB mounting pattern

●168 Contacts

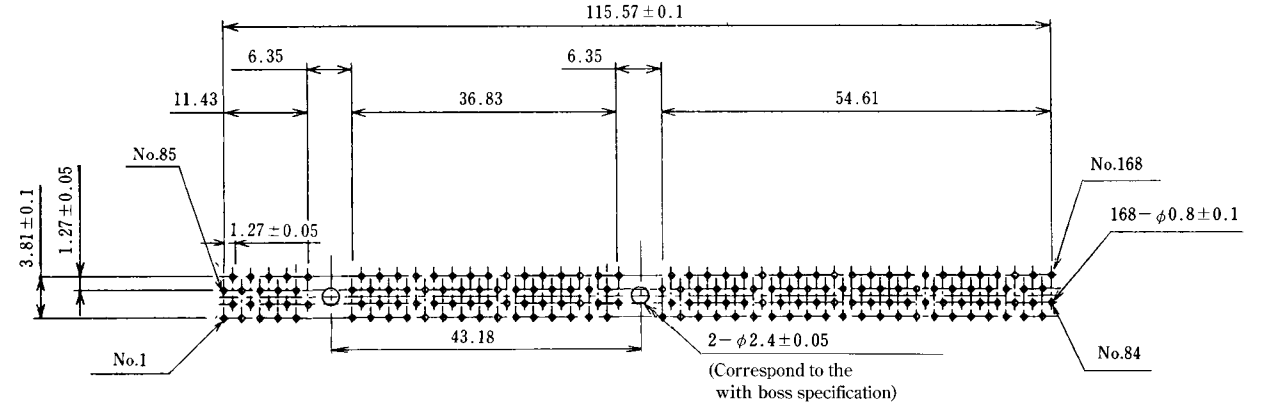
SX4AB-168S-1.27DSH



SX4BA-168S-1.27DSA,SX4AB-168S-1.27DSA

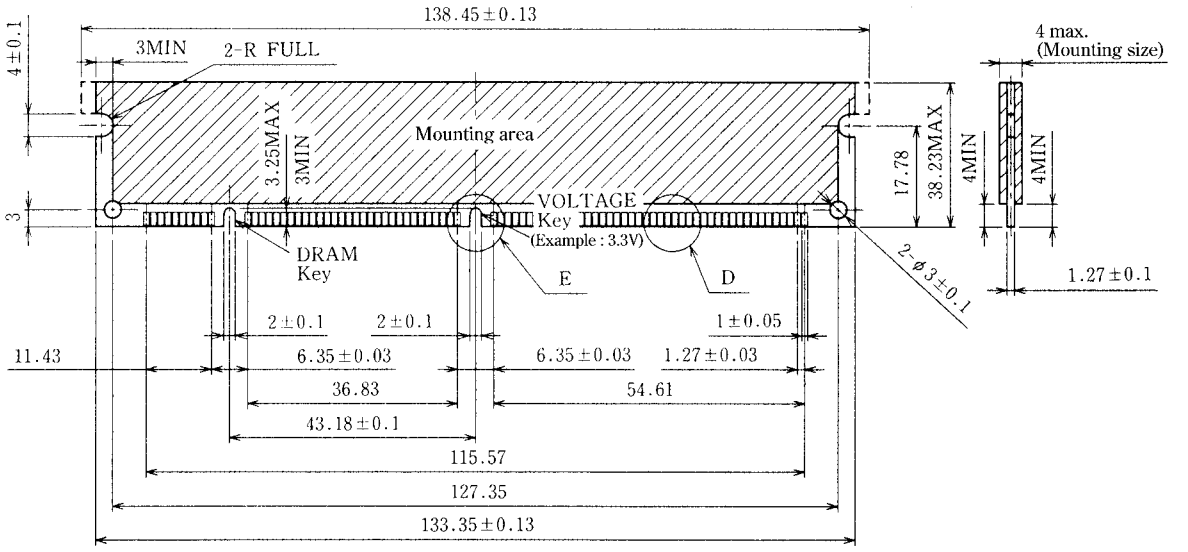


SX4BA-168S-1.27DSD

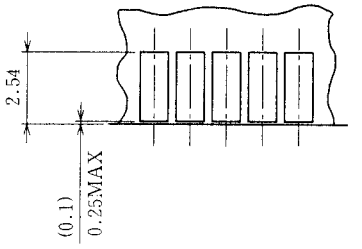


◆Recommended Module Board Dimensions

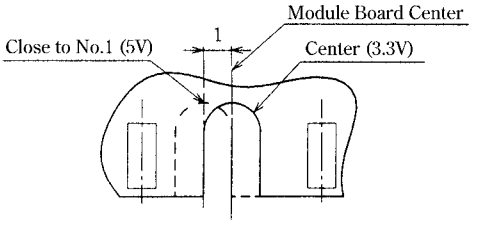
●168 Contacts



Enlarged D

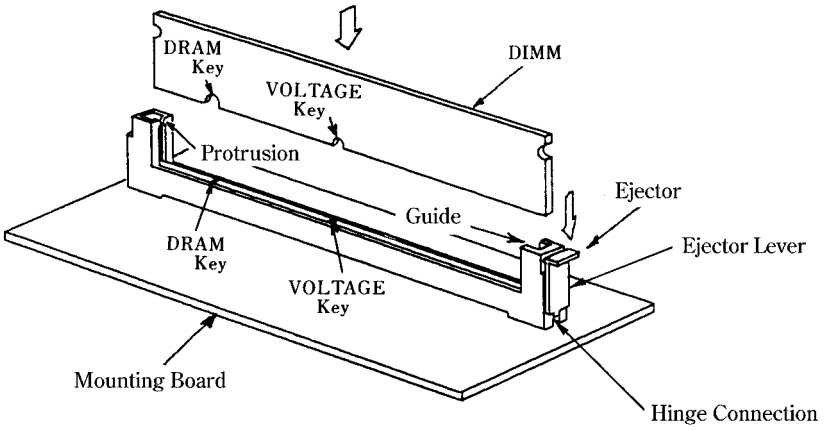


Enlarged E



■Operating Instruction

●168 Contacts



[Procedures for Board Insertion]

1. Adjust DIMM to the socket key direction.
2. Insert the DIMM along both socket sides and straight in the vertical direction to the mounting board. At this time, anti-vibration mechanism (protrusion) causes slight resistance to occur, but insert the DIMM until to hit the bottom. However, avoid slant and flap insertion, or slant engagement or half-insertion.
3. When the DIMM is inserted, it is engaged with a click tone.

[Procedures for Board Extraction]

1. Press the ejector in the vertical direction.
2. Pick up the DIMM with fingers, which floats slightly.

Precautions

1. The ejector has strength enough to endure. However, if force is applied according to other operation methods instead of the Procedures for Handling Sockets, products could be damaged.
2. This product is designed in compliance with JEDEC "8 Byte DIMM". However, if other boards are used instead of the recommended module board or if the mounting devices are used the other than memory IC, troubles due to vibration or other failures could occur. Confirm individual conditions.
3. Acute angles at pad edges of recommended module boards could cause failure in contacts. Therefore, it is recommended to offset the tie-bar (0.1mm) from the center line, set the internal pad, or remove sharp edges or burrs according to the recommended size ranges.
4. Stand-off is provided for measures to prevent flux rise, but resin sealing is not done. Confirm individual conditions.
5. If strong heat is concentrated on the product (reflow, etc.), the product will be deformed due to strength. Check individual conditions.
6. Use alcohol-based flux solvent, which does not subject chemical reaction.
7. Don't provide convex or concave portions at external edges of the module board, or and chamfer areas at both edges. Comply with the recommended sizes.
8. The dip section tip is considered for safety, the tip is slimmed for enhancement of mountability. Be careful for handling products.
9. If the board is installed under other conditions, instead of conditions indicated in the connector mounting board and installation size pattern corresponding to individual products, failure could be caused. Observe the connector mounting board and installation size pattern, corresponding to individual products.
10. Note that slant or flap insertion could cause product damage.
11. Slant engagement or half-insertion could cause circuit short or fuming.
12. If force is given regardless the "Procedures for Handling Sockets", it will cause breakage.
13. Dusts inclusion in connector engagement areas will cause failure in the product. In addition, it is recommended to install SX4-1684S-DC (use a special cover. For details, consult HRS Sales Department) in the connector, which is not equipped with the module.
14. Even if the ejector is separated from the hinge connection area, operativity of the DIMM injector is not affected. However, don't forcibly remove the ejector lever. Such a behavior could cause the ejector lever to loosen.